Specification Amendments

Please amend paragraphs [0007], [0011], [0014], and [0026] as follows:

[0007] Figures 1a through 1d depict embodiments of one of a pair of cooling system hinges and an assembly employing a pair of cooling system hinges. Assembly 150 is made up principally of a pair of cooling system hinges 100 (only one of which is visible), cooling system 160 and enclosure 170. Enclosure 170 is made up of chassis 172 and cover 176, and in various embodiments, at least part of both chassis 172 and cover 176 are made up of metal. Also, enclosure 170 is the enclosure of an electronic system having an IC within that relies on cooling system 160 to aid in removing and releasing heat generated by the IC during normal operation of the electronic system. In some embodiments, enclosure 170 is the enclosure of a computer system, and the IC relying on cooling system 160 is a processor (and in some variations, perhaps more than one processor). In some embodiments, cooling system 160 employs a liquid to conduct heat away from the IC with the liquid being circulating between a heat absorber directly attached to the IC and cooling system 160 via hoses. Cooling system 160 employs a fan, possibly within cooling system 160, itself, to force air through cooling system 160 as part of releasing heat conducted to cooling system 160 from the IC to the surrounding air. In some embodiments, air inlet 178 is formed through cover 176 at a location that is aligned with air inlet 168 of cooling system 160 through which cooling system 160 takes in air, and air outlet 174 is formed through

chassis 172 at a location that may or may not be aligned with air outlet ~~164~~ (not visible) through which cooling system 160 outputs the air taken in through air inlet 168 after heat conducted to cooling system 160 from the IC has been released by transferring it to that air.

[0011] Lock pin indicator beam 139 is positioned towards the end of the groove defined between lock pin holding beam 132 and central beam 112 that is nearest mounting base 114 to engage and releasably retain lock pin 130 in that end of the groove when cooling system 160 is pivoted to a closed position. In some embodiments, lock pin 130 may be released from such retention if sufficient force is used in pivoting cooling system 160 such that lock pin 130 is able to push against lock pin indicator beam 139 and move lock pin indicator beam 139 out of the path of lock pin 130. In other embodiments, thumb tab 135 is operated to move lock pin holding beam 132 away from central beam 112 so as to widen the path of lock pin 130 enough to enable lock pin 130 to move past lock pin indicator beam 139. In some embodiments, lock pin indicator beam 139 is positioned such that lock pin 130 is releasably retained between lock pin indicator beam 139 and lock pin holding beam 132 (as depicted). In other embodiments, lock pin indicator beam 139 is positioned such that lock pin 130 is releasably retained between lock pin indicator beam 139 and central beam 112. In some embodiments, lock pin indicator beam 139 is configured to engage lock pin 130 such that onset and release of the force required to move lock pin 130 past lock pin indicator beam 139 provides positive

tactile feedback that confirms to ~~an~~ a person pivoting cooling system 160 that lock pin 130 has been moved into and/or out of releasable retention effected by lock pin indicator beam 139. Also, in some embodiments, the lock pin indicator beam 139 is provided to aid in retaining cooling system 160 in the closed position such that the position of cooling system 160 does not impede the opening and/or closure of enclosure 170 through the removal and/or installation of cover 176. Keeping cooling system 160 out of the path of cover 176 may be particularly desirable if the removal and/or installation of cover 176 entails some degree of sliding of cover 176 relative to chassis 172.

[0014] Figure 2 depicts an embodiment of hinge mount. Similarly to hinge mount 110 of Figures 1a-d, hinge mount 210 is made up principally of mounting base 214 with central beam 212, hinge pin holding beam 222, lock pin holding beam 232 and lock pin indicator beam 239 emanating from mounting base 214. Mounting base 214 provides mounting points ~~115~~ 215 by which mounting base 214 of hinge mount 210 may be attached to a portion of a chassis (not shown). In some embodiments, mounting points 215 are made up of multiple holes formed through mounting base 214 through which rivets, screws, etc. may be inserted as part of making the attachment of mounting base 214 to a portion of a chassis. However, as those skilled in the art will readily recognize, alternate embodiments may employ alternate forms of mounting points 215 that use any of a variety of mechanisms to attach mounting base 214 to a portion of a chassis are

possible without departing from the spirit and scope of the claimed invention. In some embodiments, hinge mount 210 is made from injection-molded plastic or similar material, thereby electrically isolating a liquid-based cooling system from a chassis into which the cooling system is installed such that electric currents that might be conducted through cooling liquid between a heat absorber attached to an IC being cooled within the chassis and the cooling system are not allowed to be further conducted between the cooling system and the chassis, thereby aiding in the prevention of galvanic corrosion and/or the creation of ground loops.

[0026] Figures 4a through 4c depict embodiments of one of a pair of cooling system hinges and an assembly employing a pair of cooling system hinges. Assembly 450 is made up principally of a pair of cooling system hinges 400, cooling system 460 and enclosure 470. Enclosure 470 is made up of chassis 472 and cover 476, and in various embodiments, at least part of both chassis 472 and cover 476 are made up of metal. Also, enclosure 470 is the enclosure of an electronic system having an IC within that relies on cooling system 460 to aid in removing and releasing heat generated by the IC during normal operation of the electronic system. In some embodiments, enclosure 470 is the enclosure of a computer system, and the IC relying on cooling system 460 is a processor (and in some variations, perhaps more than one processor). In some embodiments, cooling system 460 employs a liquid to conduct heat away from the IC with the

liquid being circulating between a heat absorber directly attached to the IC and cooling system 460 via hoses. Cooling system 460 employs a fan, possibly within cooling system 460, itself, to force air through cooling system 460 as part of releasing heat conducted to cooling system 460 from the IC to the surrounding air. In some embodiments, air inlet 478 is formed through cover 476 at a location that is aligned with air inlet 468 of cooling system 460 through which cooling system 460 takes in air, and air outlet 474 is formed through chassis 472 at a location that is aligned with air outlet ~~464~~ (not visible) through which cooling system 460 outputs the air taken in through air inlet 468 after heat conducted to cooling system 460 from the IC has been released by transferring it to that air. In alternate embodiments, air inlet ~~464~~ 468 is not aligned with an air inlet on any part of the exterior of enclosure 470, but is instead, positioned on a portion of the surface of cooling system 460 that allows cooling system 460 to draw in air from within the interior of enclosure 470 to cause air flow within enclosure 470 to cool components within enclosure 470.